

Amendments to the Claims

This listing of claims will replace all prior version, and listings, of claims in the application.

Listing of Claims:

1. (currently amended) A multi-layer semiconductor chip package, comprising:
~~a first plurality of pairs of conductors for carrying a plurality of first signals in a layer of a carrier of the package; and, wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors affect each other evenly, wherein a second pair of conductors for carrying a second signal adjacent to the first pair of conductors in the layer, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.~~
2. – 4. (canceled)
5. (currently amended) The package of claim [4] 1, wherein the ~~first and second adjacent~~ pairs of conductors are positioned orthogonally to each other.
6. (currently amended) The package of claim [4] 1, wherein the ~~second adjacent~~ pairs of conductors ~~is~~ are positioned to be equidistant to each ~~other~~ conductor in the first pair of conductors.
7. (original) The package of claim 1, wherein the layer is near an interface between the carrier and a chip.

8. – 14. (canceled)

15. (currently amended) A connector capable of being coupled to a semiconductor chip package, comprising:

~~a first plurality of pairs of conductors for carrying a plurality of first signals in a layer of a carrier of the package, and, wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors affect each other evenly, wherein~~
~~a second pair of conductors for carrying a second signal adjacent to the first pair of conductors, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.~~

16. (canceled)

17. (currently amended) The connector of claim 16 ~~15~~, wherein the second adjacent pairs of conductors ~~is~~ are positioned to be equidistant to each ~~other~~ conductor in the first pair of conductors.

18. (currently amended) A method for providing a semiconductor chip package, comprising the steps of:

(a) providing a first plurality of pairs of conductors for carrying a first plurality of signals in a layer of a carrier of the package, and, ~~wherein each pair of conductors in the layer is positioned so that adjacent pairs of conductors affect each other evenly, wherein~~
(b) ~~providing a second pair of conductors for carrying a second signal adjacent to the~~

~~first pair of conductors in the layer, wherein the first and second pairs of conductors are configured such that cross-talk between the first and second the adjacent pairs of conductors is substantially minimized without increasing a size of the package.~~

19. – 21. (canceled)

22. (currently amended) The method of claim ~~21~~ 18, wherein the ~~second adjacent~~ pairs of conductors ~~is~~ are positioned to be equidistant to each ~~other~~ conductor in the first pair of conductors.

23. (original) The method of claim 18, wherein the layer is near an interface between the carrier and a chip.